

English ▼

Search Microchip

Search Data Sheets

PRODUCTS **APPLICATIONS** **DESIGN SUPPORT** **TRAINING** **SAMPLE & BUY** **ABOUT US** [Contact Us](#) [myMicrochip Login](#)

Product Change Notification - JAON-09SEEU093 [\(Printer Friendly\)](#)

Date: 17 Dec 2014

Notification subject: CCB 1155.35 Initial Notice: Qualification of palladium coated copper (PdCu) bond wire and 3280 die attach epoxy in selected products of the 200K wafer technology available in 28L SSOP package at MTAI

Notification text: **PCN Status:**
Initial notification

Microchip Parts Affected:

See attachments of affected catalog part numbers (CPN) labeled as...

[PCN_JAON-09SEEU093_Affected_CPN.xls](#)

[PCN_JAON-09SEEU093_Affected_CPN.pdf](#)

Description of Change:

Qualification of palladium coated copper (PdCu) bond wire and 3280 die attach epoxy in selected products of the 200K wafer technology available in 28L SSOP package at MTAI assembly site.

NOTE: Selected products are non-automotive devices. Please review the affected CPN lists (attached) to identify the actual parts affected.

Pre Change:

Gold wire and 8390A die attach epoxy

Post Change:

PdCu wire and 3280 die attach epoxy

Impacts to Data Sheet:

None

Reason for Change:

To improve manufacturability and qualify PdCu bond wire at MTAI assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

January 23, 2015 (date code: 1504)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Markings to Distinguish Revised from Unrevised Devices:

Traceability code

Revision History:

December 17, 2014: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): [PCN_JAON-09SEEU093_Qual_Plan.pdf](#)
[PCN_JAON-09SEEU093_Affected_CPN.pdf](#)
[PCN_JAON-09SEEU093_Affected_CPN.xls](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to change your product/process change notification (PCN) profile please log on to our website at <http://www.microchip.com/PCN> sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to [microchipDIRECT](#) and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

